

HyperX Genesis | KHX1600C9D3K2/8GX



DESCRIPTION

Kingston's KHX1600C9D3K2/8GX is a kit of two 512M x 64-bit(4GB) DDR3-1600 CL9 SDRAM (Synchronous DRAM) 2Rx8 memory modules, based on sixteen 256M x 8-bit DDR3 FBGA components per module. Each module kit supports Intel® XMP(Extreme Memory Profiles). Total kit capacity is 8GB. Each module kit has been tested to run at DDR3-1600 at a low latency timing of 9-9-9-27 at 1.65V. The SPDs are programmed to JEDEC standard latency DDR3-1333 timing of 9-9-9 at 1.5V. Each 240-pin DIMM uses gold contact fingers and requires +1.5V.

FEATURES

- JEDEC standard 1.5V (1.425V ~ 1.575V) Power Supply
- VDDQ = 1.5V (1.425V ~ 1.575V)
- 667MHz fCK for 1333Mb/sec/pin
- 8 independent internal bank
- Programmable CAS Latency: 9, 8, 7, 6
- Posted CAS
- Programmable Additive Latency: 0, CL - 2, or CL - 1 clock
- Programmable CAS Write Latency(CWL) = 7 (DDR3-1333)
- 8-bit pre-fetch
- PCB : Height 1.180" (30.00mm), double sided component
- Bi-directional Differential Data Strobe
- Burst Length: 8 (Interleave without any limit, sequential with starting address "000" only), 4 with tCCD = 4 which does not allow seamless read or write [either on the fly using A12 or MRS]
- Internal(self) calibration : Internal self calibration through ZQ pin (RZQ : 240 ohm \pm 1%)
- On Die Termination using ODT pin
- Average Refresh Period 7.8us at lower than TCASE 85°C, 3.9us at 85°C < TCASE < 95°C
- Asynchronous Reset